

Ceramic Plate Series Thermoelectric Cooler

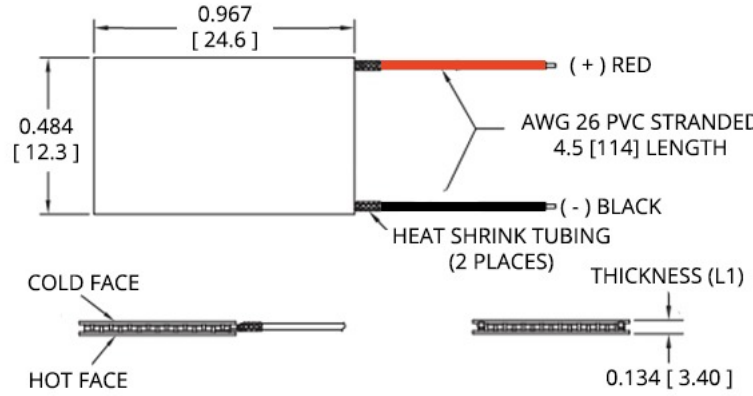
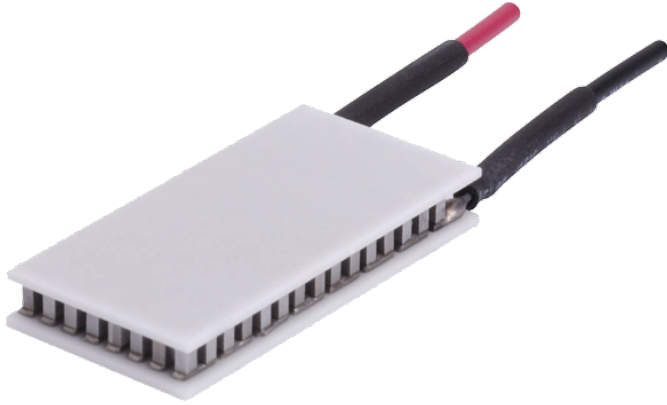
The CP08-63-06-L1-EP-W4.5 is a high-performance and highly reliable standard Thermoelectric Cooler. Assembled with Bismuth Telluride semiconductor material and thermally conductive Aluminum Oxide ceramics. It has a maximum Q_c of 8.7 Watts when $\Delta T = 0$ and a maximum ΔT of 70.5 °C at $Q_c = 0$.

Features

- Compact geometric sizes
- DC Operation
- RoHS-compliant

Applications

- Thermoelectric Coolers for Reagent Storage
- Thermoelectric Coolers for Handheld Cosmetic Lasers
- Cooling for Centrifuges
- Heads-Up Displays, Imaging Sensors
- Peltier Cooling for Machine Vision



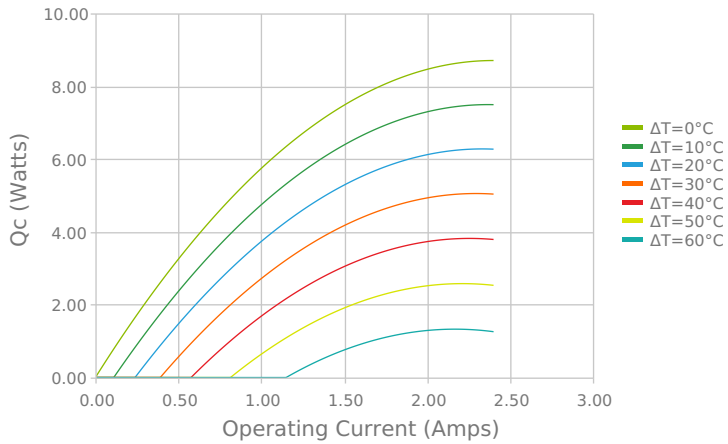
Ceramic Material: Alumina (Al_2O_3)
 Solder Construction: 138°C, Bismuth Tin (BiSn)

INCHES [MM]

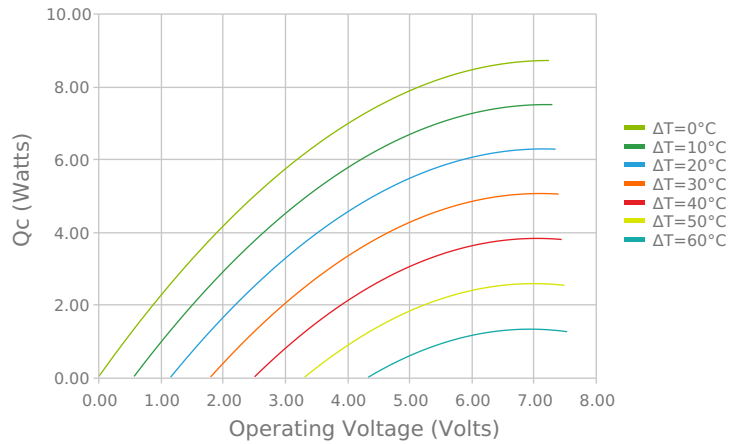
Note: Allow 0.020 in [0.5 mm] around perimeter of the thermoelectric cooler and lead wire attachment to accommodate sealant

ELECTRICAL AND THERMAL PERFORMANCE

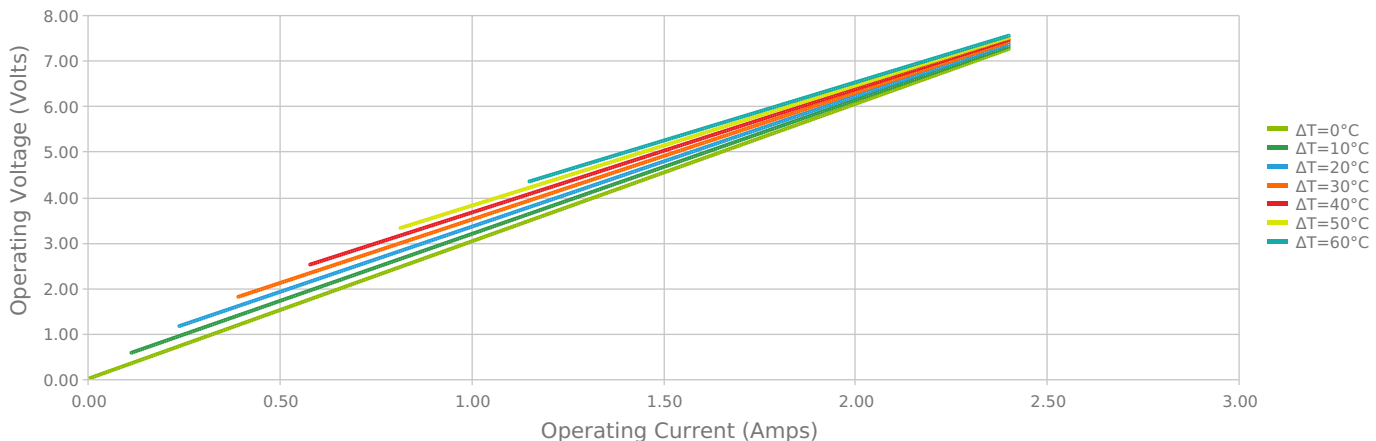
Heat Pumped at Cold Side
 $T_{hot} = 27\text{ °C}$



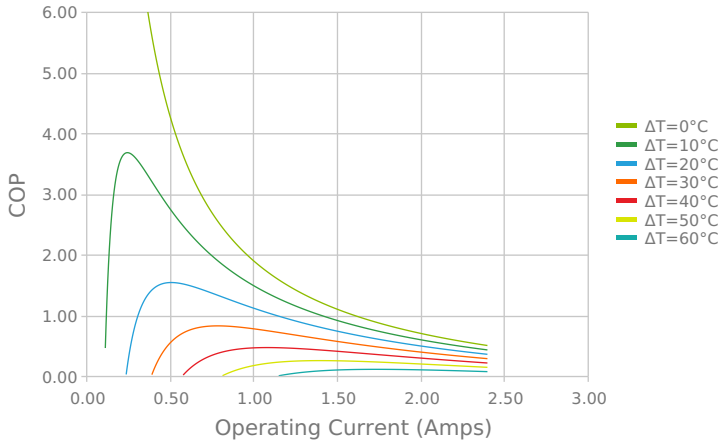
Heat Pumped at Cold Side
 $T_{hot} = 27\text{ °C}$



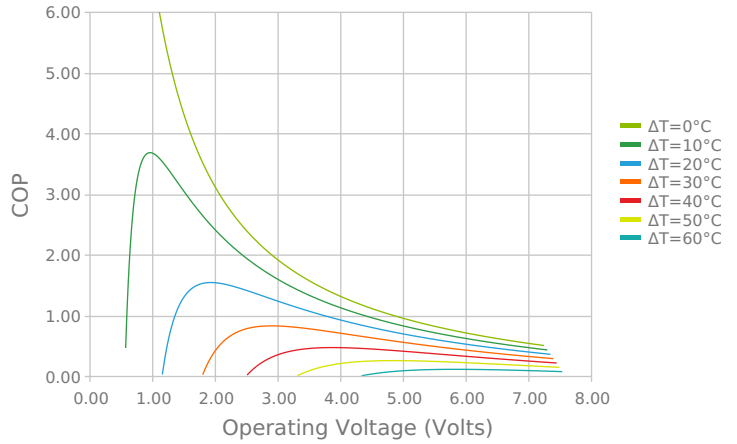
Current vs Voltage (I vs V)
 $T_{hot} = 27\text{ °C}$



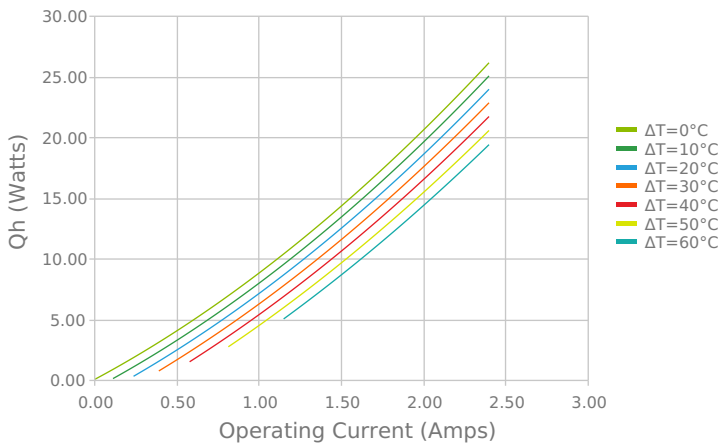
Coefficient of Performance (COP = Qc/Pin)
 Thot = 27 °C



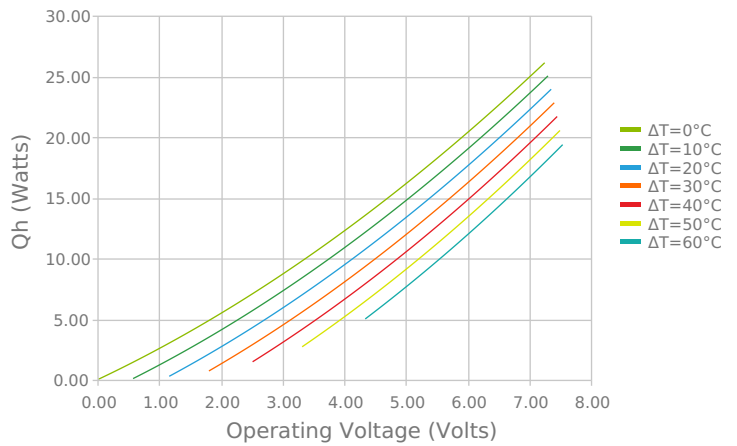
Coefficient of Performance (COP = Qc/Pin)
 Thot = 27 °C



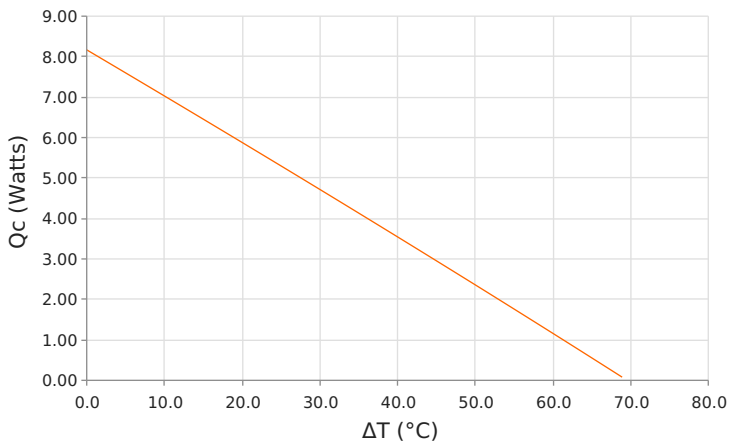
Total Heat Dissipated at Hot Side (Qh=Qc+Pin)
 Thot = 27 °C



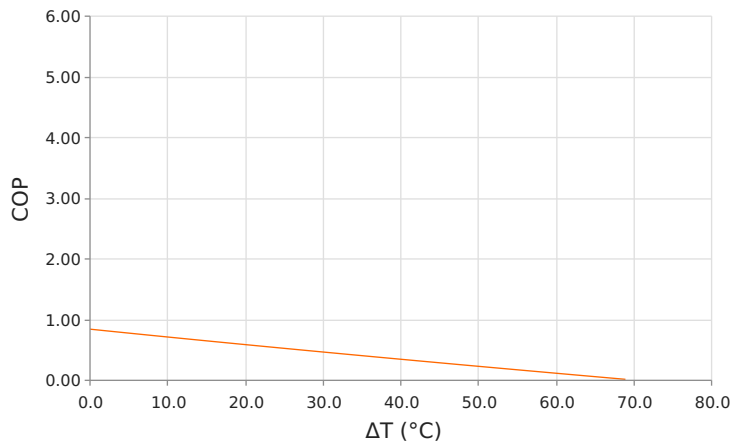
Total Heat Dissipated at Hot Side (Qh=Qc+Pin)
 Thot = 27 °C



Heat Pumped at Cold Side (Qc)
 Thot = 27 °C | Current = 1.8 Amps



Coefficient of Performance (COP = Qc/Pin)
 Thot = 27 °C | Current = 1.8 Amps



SPECIFICATIONS*

Hot Side Temperature	27.0 °C	35.0 °C	50.0 °C
Qcmax ($\Delta T = 0$)	8.7 Watts	9.0 Watts	9.4 Watts
ΔT_{max} ($Q_c = 0$)	70.5°C	73.5°C	78.8°C
I_{max} (I @ ΔT_{max})	2.1 Amps	2.1 Amps	2.1 Amps
V_{max} (V @ ΔT_{max})	6.9 Volts	7.1 Volts	7.6 Volts
Module Resistance	3.02 Ohms	3.15 Ohms	3.38 Ohms
Max Operating Temperature	80 °C		
Weight	4.0 gram(s)		

* Specifications reflect thermoelectric coefficients updated March 2020

FINISHING OPTIONS

Suffix	Thickness	Flatness / Parallelism	Hot Face	Cold Face	Lead Length
L1	3.403 ±0.025 mm 0.134 ± 0.001 in	0.025 mm / 0.025 mm 0.001 in / 0.001 in	Lapped	Lapped	114.3 mm 4.50 in

SEALING OPTIONS

Suffix	Sealant	Color	Temp Range	Description
EP	Epoxy	Black	-55 to 150°C	Low density syntactic foam epoxy encapsulant

NOTES

1. Max operating temperature: 80°C
2. Do not exceed I_{max} or V_{max} when operating module
3. Reference assembly guidelines for recommended installation
4. Solder tinning also available on metallized ceramics

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